

Development of Kyoto's X-ray Astronomical SOI pixel sensor

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Publication

Ryu et al.	IEEE NSS 2010, Conf. Record	XRPIXI-CZ -FI
Ryu et al.	IEEE TNS 58, 2528 (2011)	XRPIXI-CZ-FI
Tsuru et al.	IEEE NSS 2011	Review
Ryu et al.	IEEE NSS 2011, Conf. Record	Event-Driven Readout system
Nakashima et al.	IEEE NSS 2011, Conf. Record	XRPIX-ADCI
Nakashima et al.	Physics Procedia 37, 1373 (2012)	XRPIXI-FZ-FI
Ryu et al.	IEEE TNS 60, 465 (2013)	XRPIXIb-CZ-FI, Inter-pixel cross-talk
Takeda et al.	IEEE TNS 60, 586 (2013)	Event-Driven Readout with XRPIXIb-CZ-FI
Tsuru et al.	SPIE Astro2012	Review
Nakashima et al.	NIM A, Accepted (2013)	XRPIX2

Talk Plan

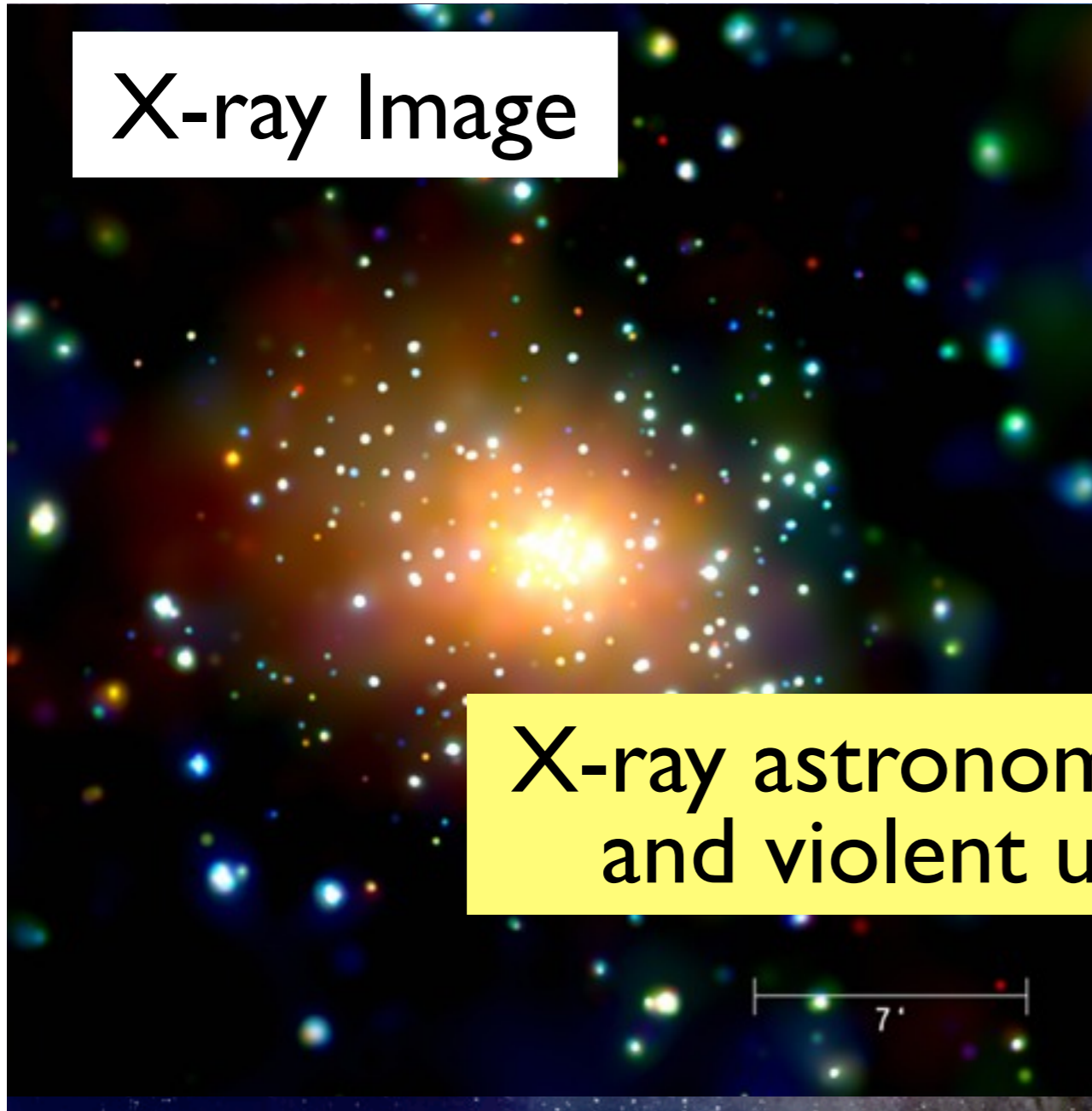
- X-ray Astronomy
- “XRPIX”
Kyoto’s X-ray Astronomical SOI pixel sensor
- Depletion Layer and Dark current
 - FZ of 2010 and 2012
- Spectral Performance
- Back Illumination
- Coming Soon

Why X-ray Astronomy ?

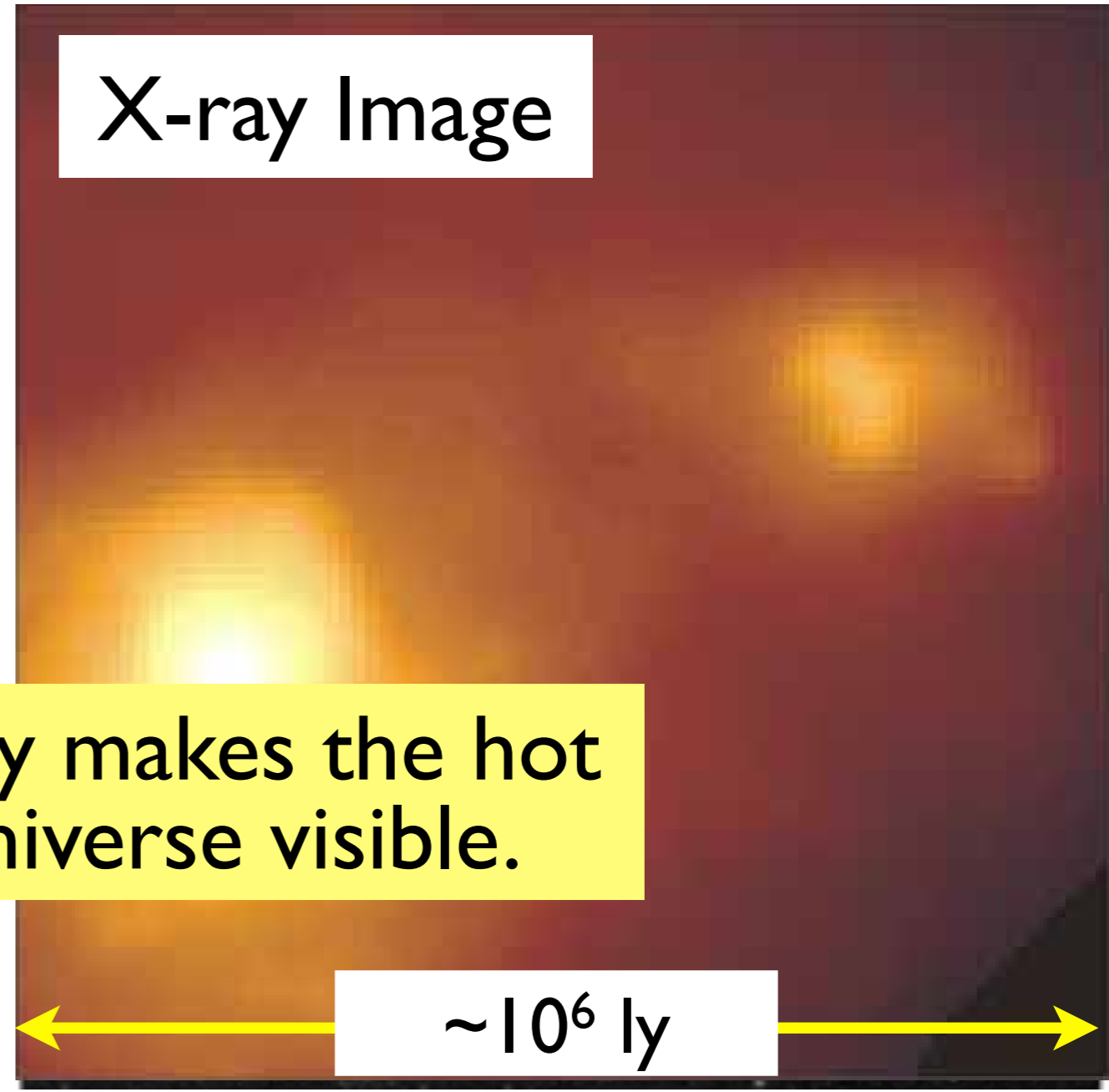
The Andromeda Galaxy

Cluster of Galaxies

X-ray Image



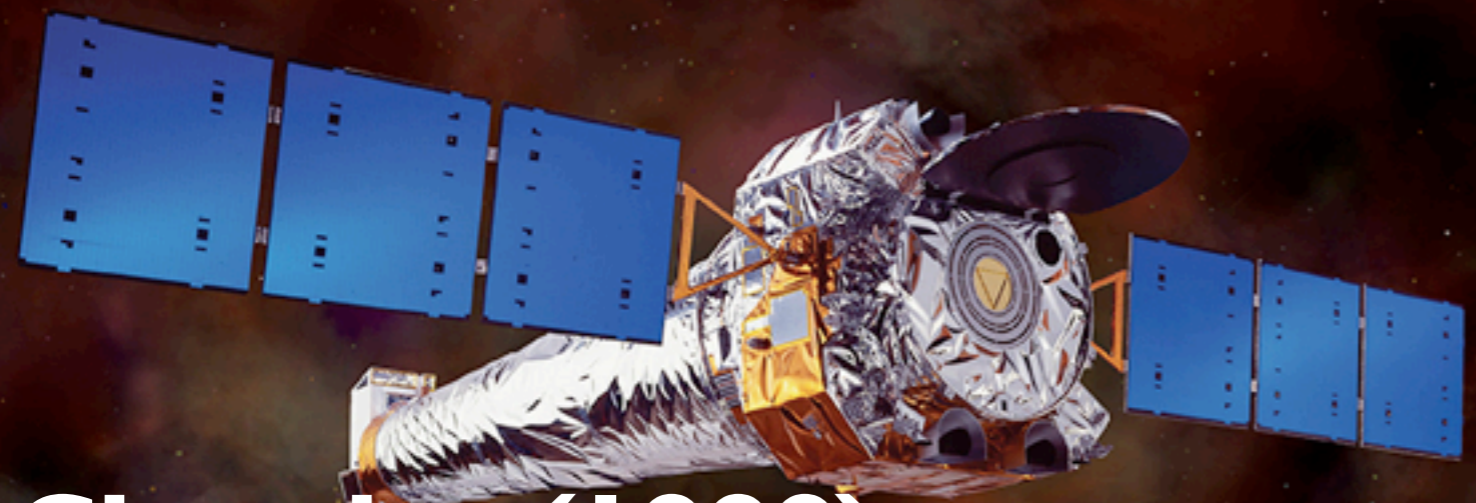
X-ray Image



X-ray astronomy makes the hot and violent universe visible.

$\sim 10^6$ ly

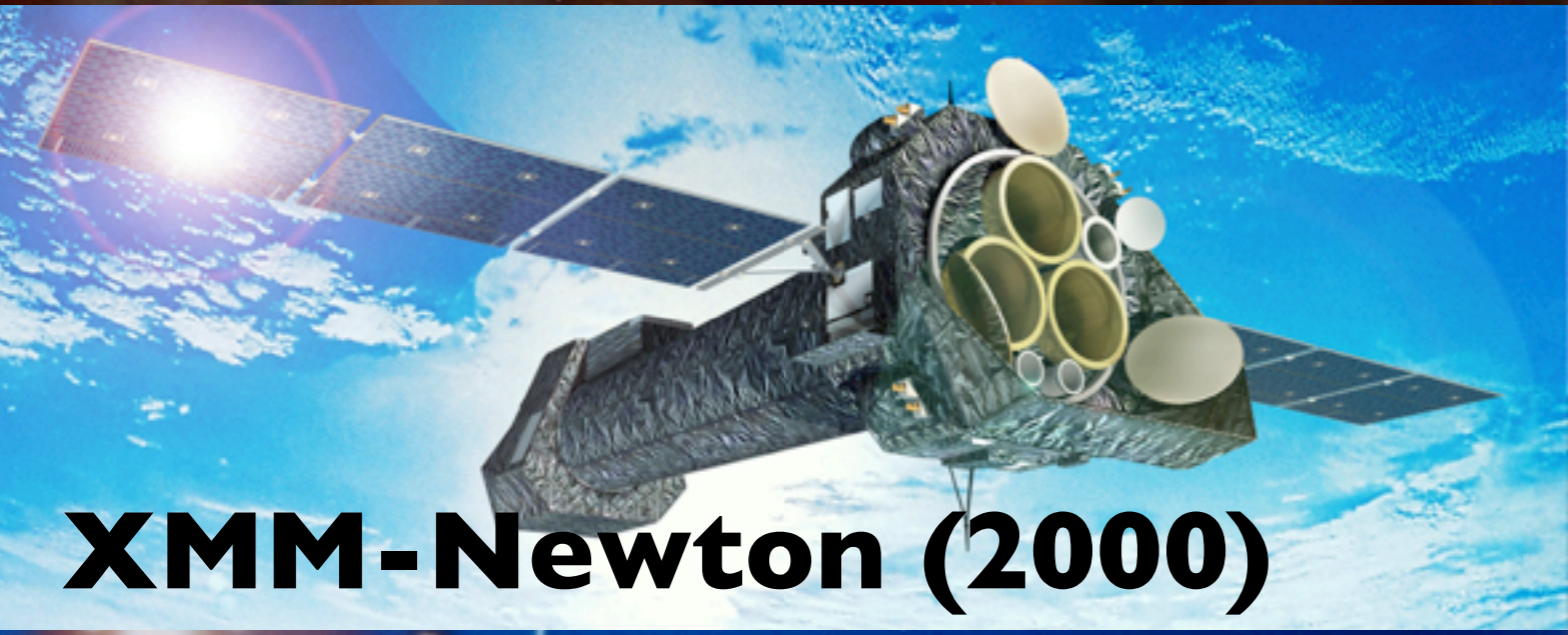
- Stars like the sun in the optical.
- Blackholes and neutron stars in X-ray.
- Hot plasma = several x sum of galaxies.
- Most of normal (baryonic) matter in the universe is visible ONLY in X-ray.



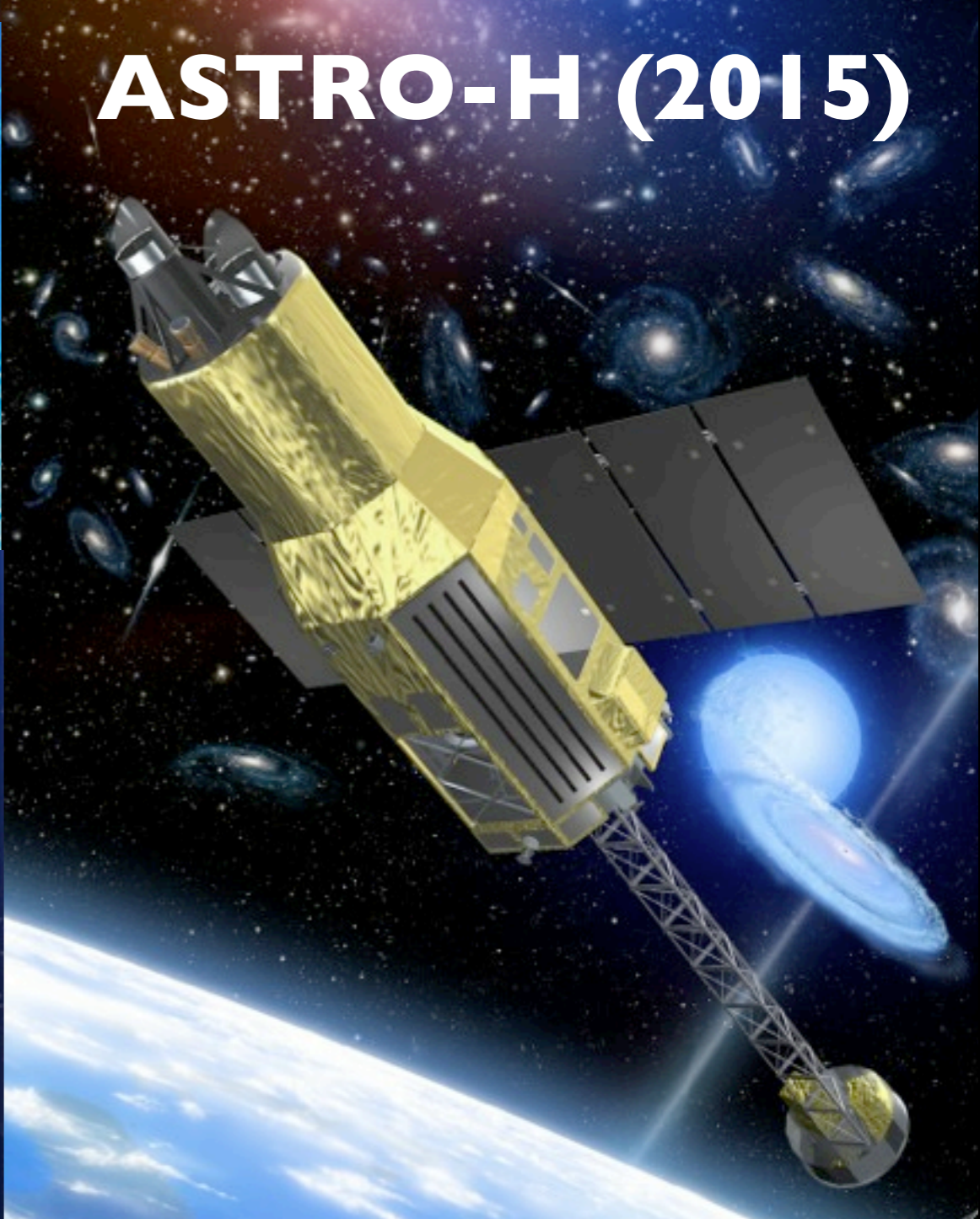
Chandra (1999)

X-ray CCD

“The” standard Imaging Spectrometer



XMM-Newton (2000)



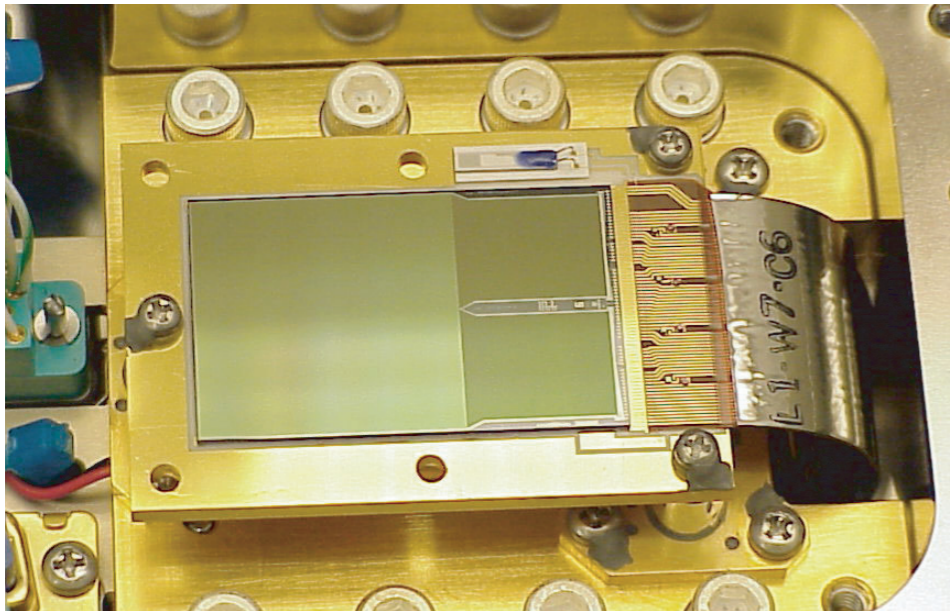
ASTRO-H (2015)



Suzaku (2005)

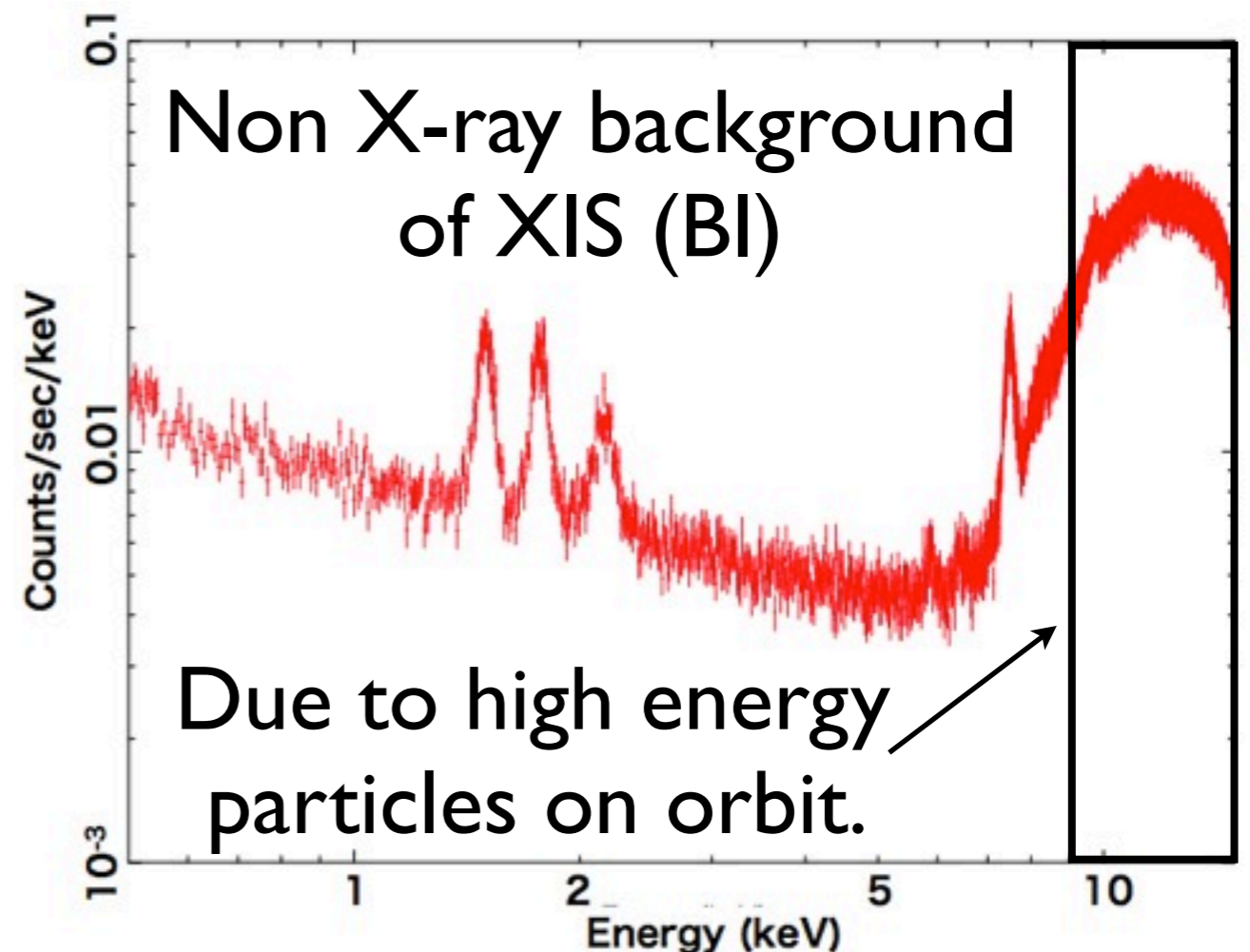
The standard Imaging Spectrometer of modern X-ray astronomical satellites X-ray CCD

Suzaku 「すざく」 XIS

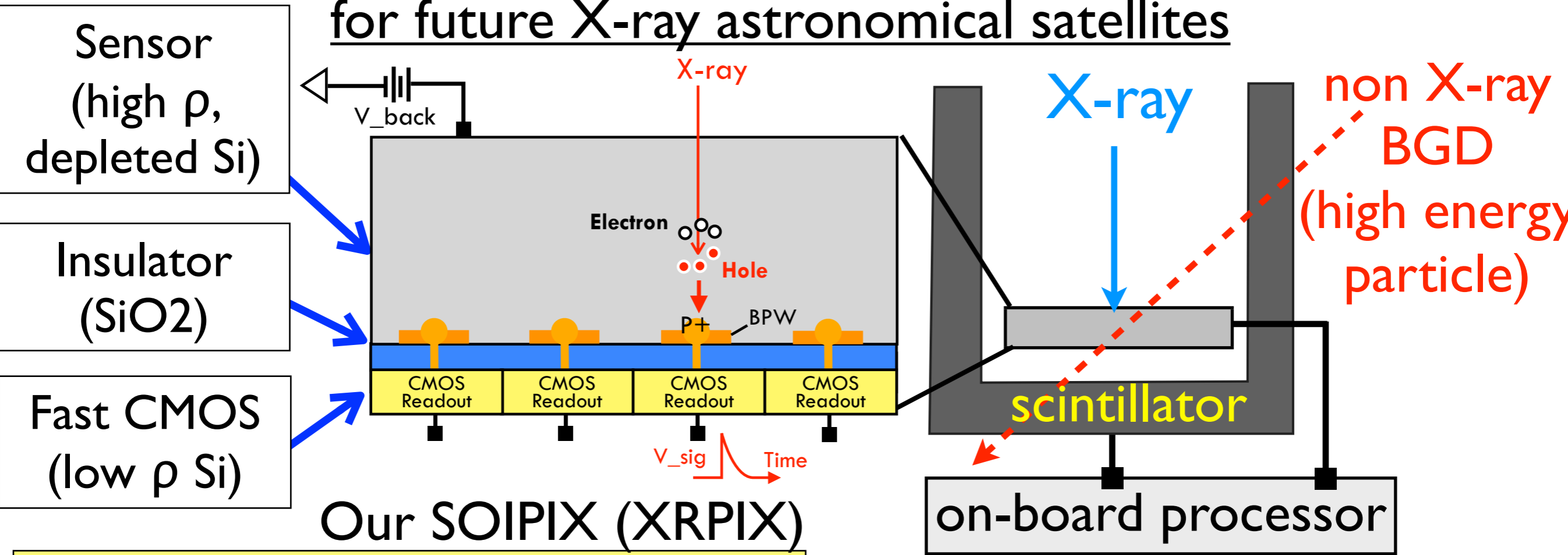


- Fano limited spectroscopy with the readout noise $\sim 3e^-$ (rms).
- Wide and fine imaging with the sensor size of $\sim 20\text{-}30\text{mm}$ pixel size of $\sim 30\mu\text{m}$ □

- **Non X-ray background** above 10keV is too high to study faint sources.
- **The time resolution** is too poor ($\sim \text{sec}$) to make fast timing observation of time variable sources.



“XRPIX” = **Monolithic** SOI pixel sensor for future X-ray astronomical satellites



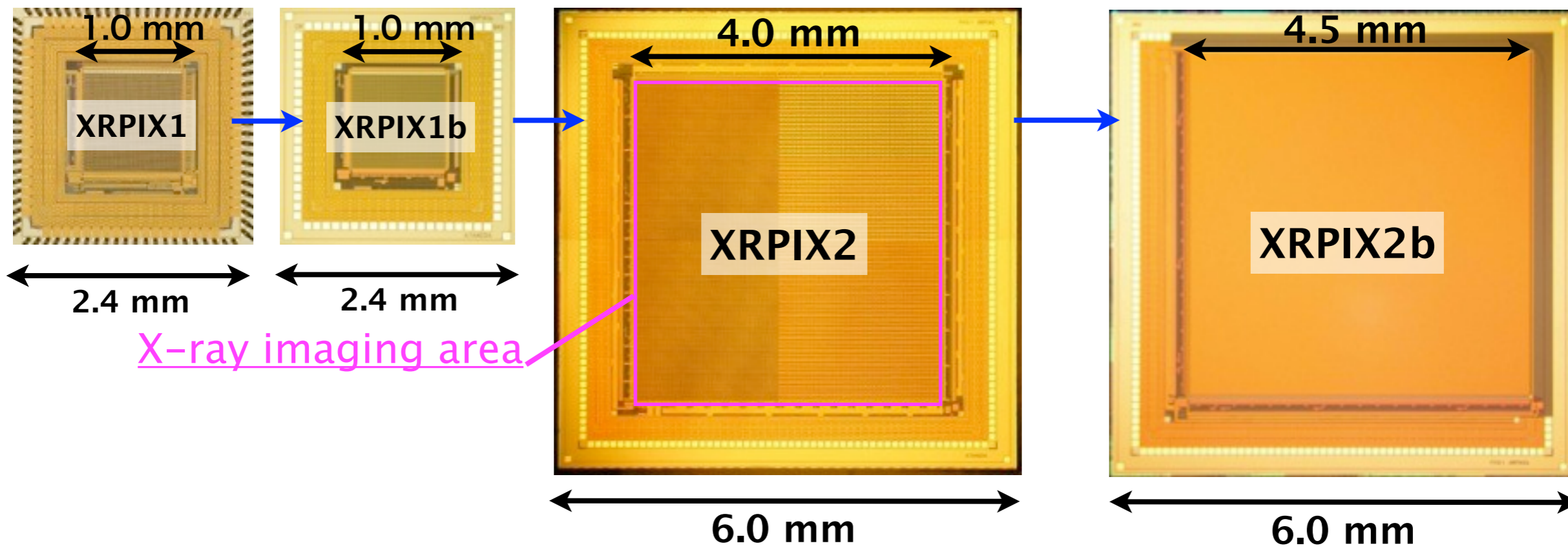
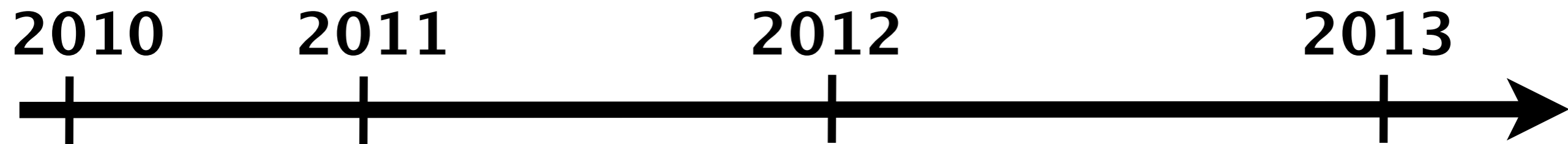
Our SOIPIX (XRPIX)

Each pixel has its own trigger and analogue readout CMOS circuit.

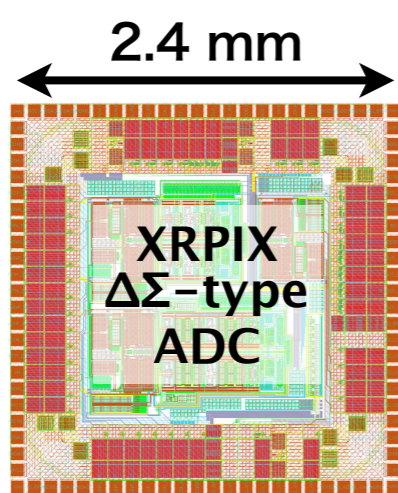
Very low BGD by anti-coincidence (1/100 of CCD at 20keV)

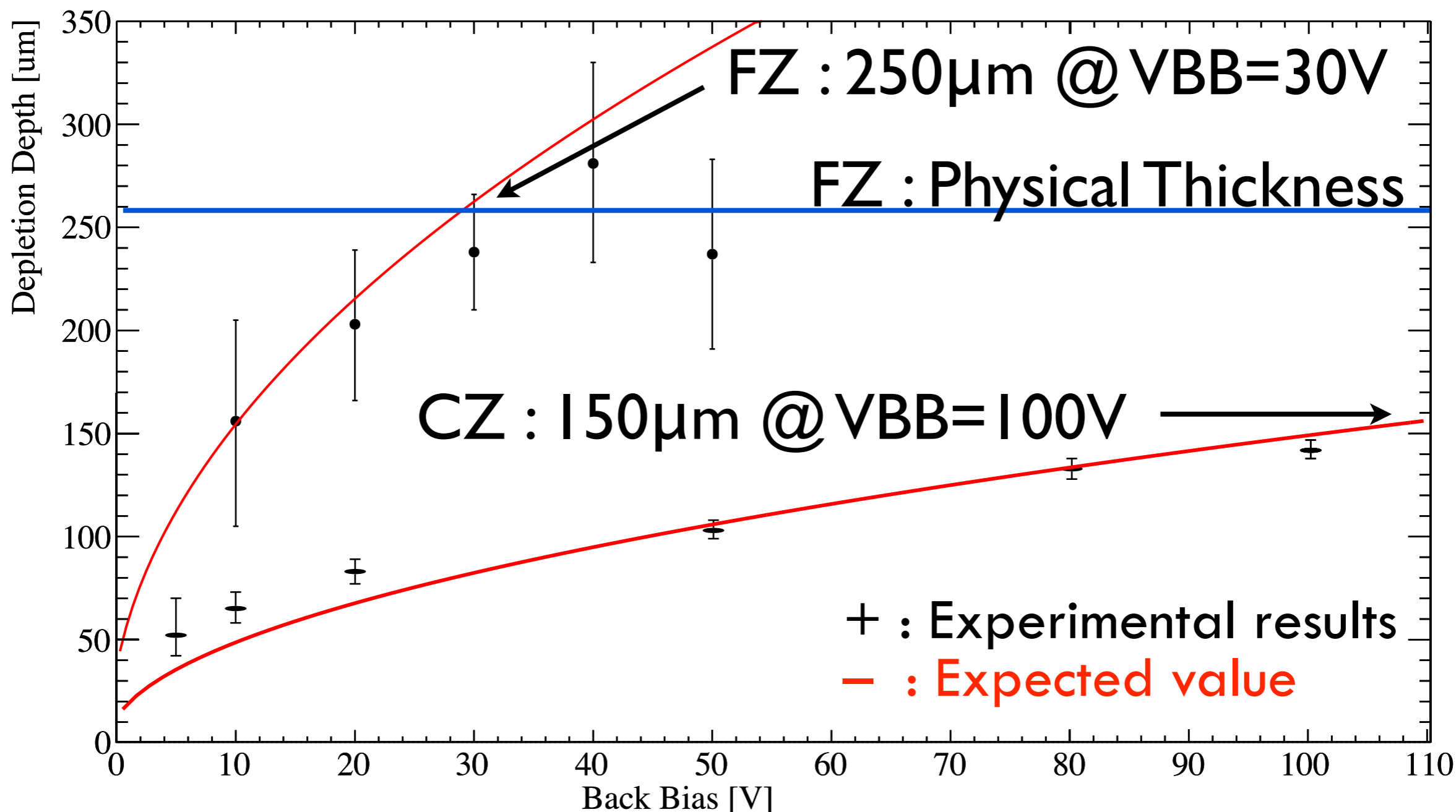
Target Spec.	Imaging	area > 25x25mm ² , pixel ~ 30-60μm ² (1" @ F=9m)
	Energy Band	0.3-40keV with BI (<0.1μm), and thick depletion (>250μm)
	Spectroscopy	ΔE < 140eV @ 6keV, Fano limit (Req.<10e-, Goal < 3e-)
	Timing	<1μsec
	Dark Current	<2pA/cm ² (assuming working T = -40°C)
	Function	Trigger signal & pixel address output, built-in ADC
	Non X-ray BGD	5e-5 c/s/keV/10x10mm ² at 20keV (1/100 of CCD)

XRPIX Series – Road Map –



X-ray imaging area

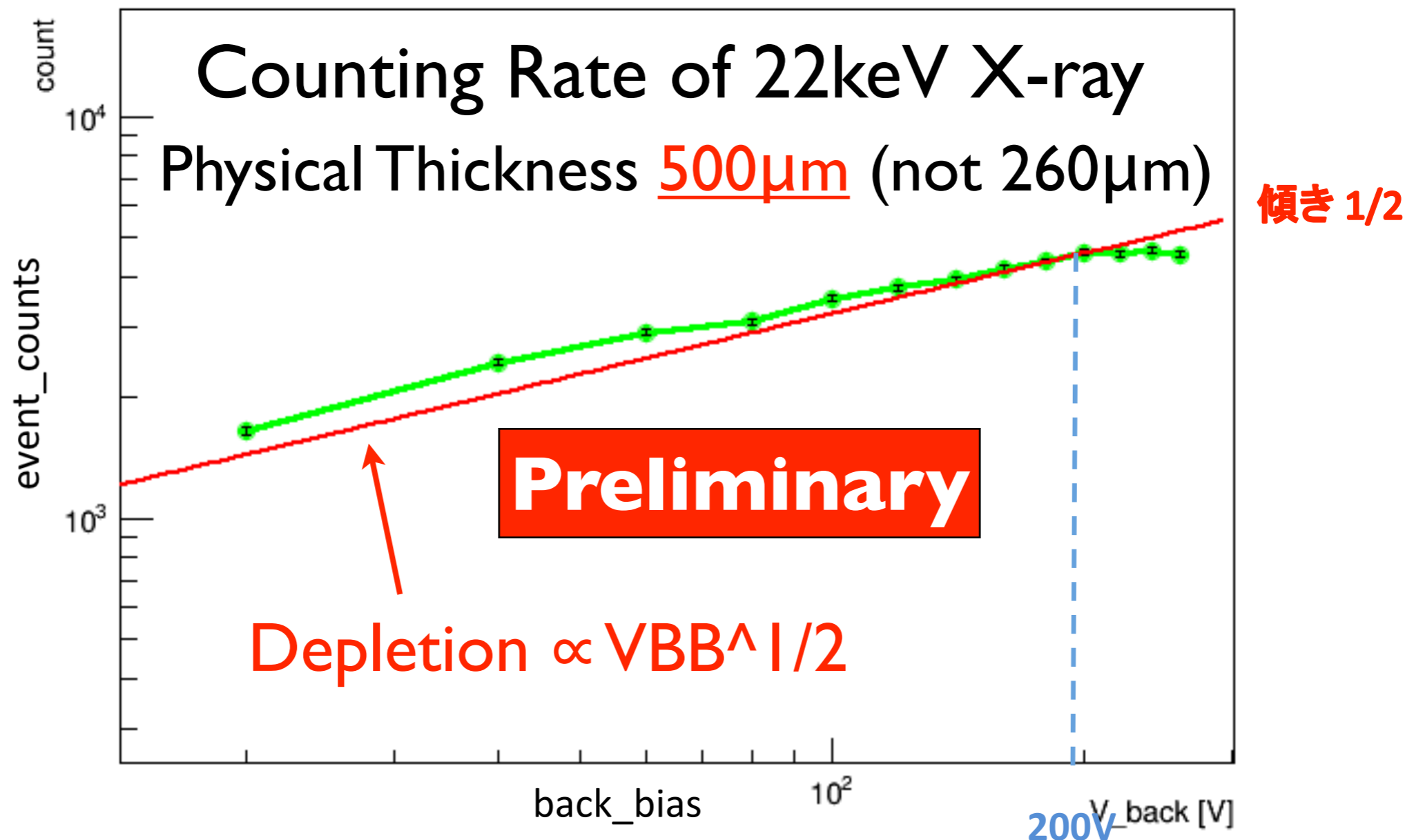




• Measure the depletion thickness by observing the ratio between the counting rates of two energies X-rays having different attenuation lengths.

• CZ: Depletion thickness of 150μm at VBB=100V.

• FZ: Full depletion of 250μm is achieved at VBB=30V.



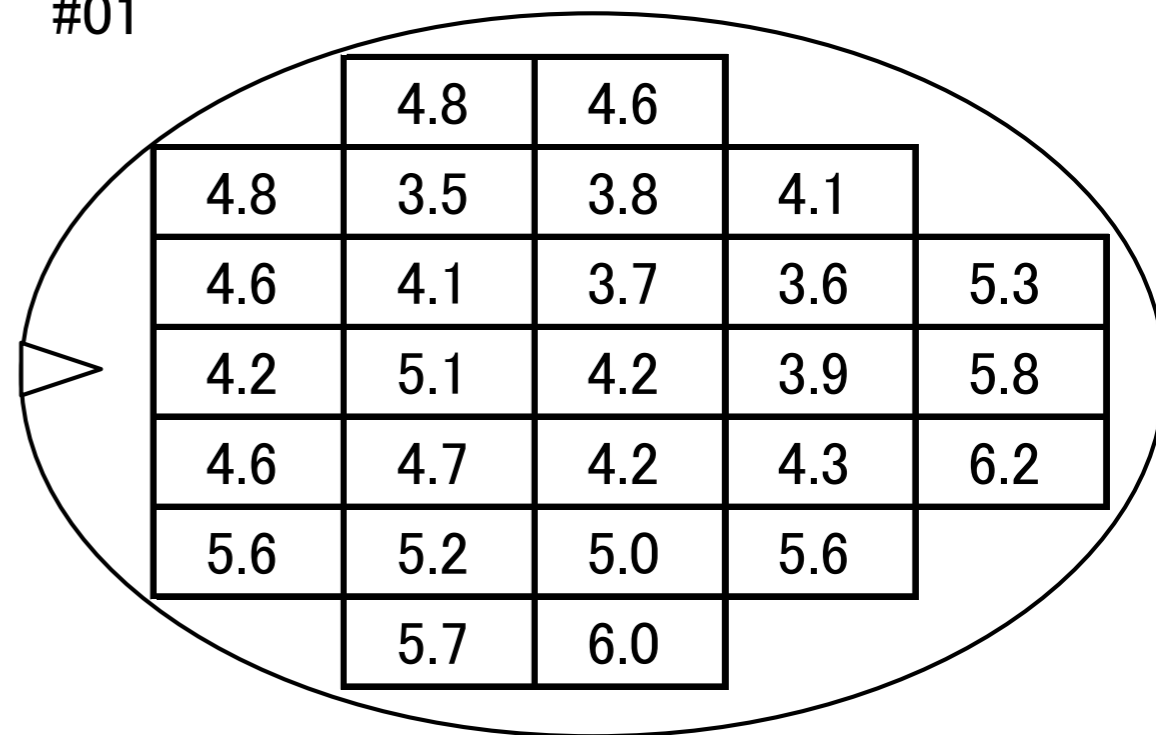
- Counting Rate of 22keV X-ray (Cd-109) as a function of VBB. (Attenuation Length = 1200μm > Physical Thickness = 500μm.)
- The data follow the expected slope of depletion $\propto VBB^{1/2}$.
- Full Depletion is reached at VBB=200V.

XRPIX1b-FZ(2012)-FI (7kΩcm) : Depletion Depth

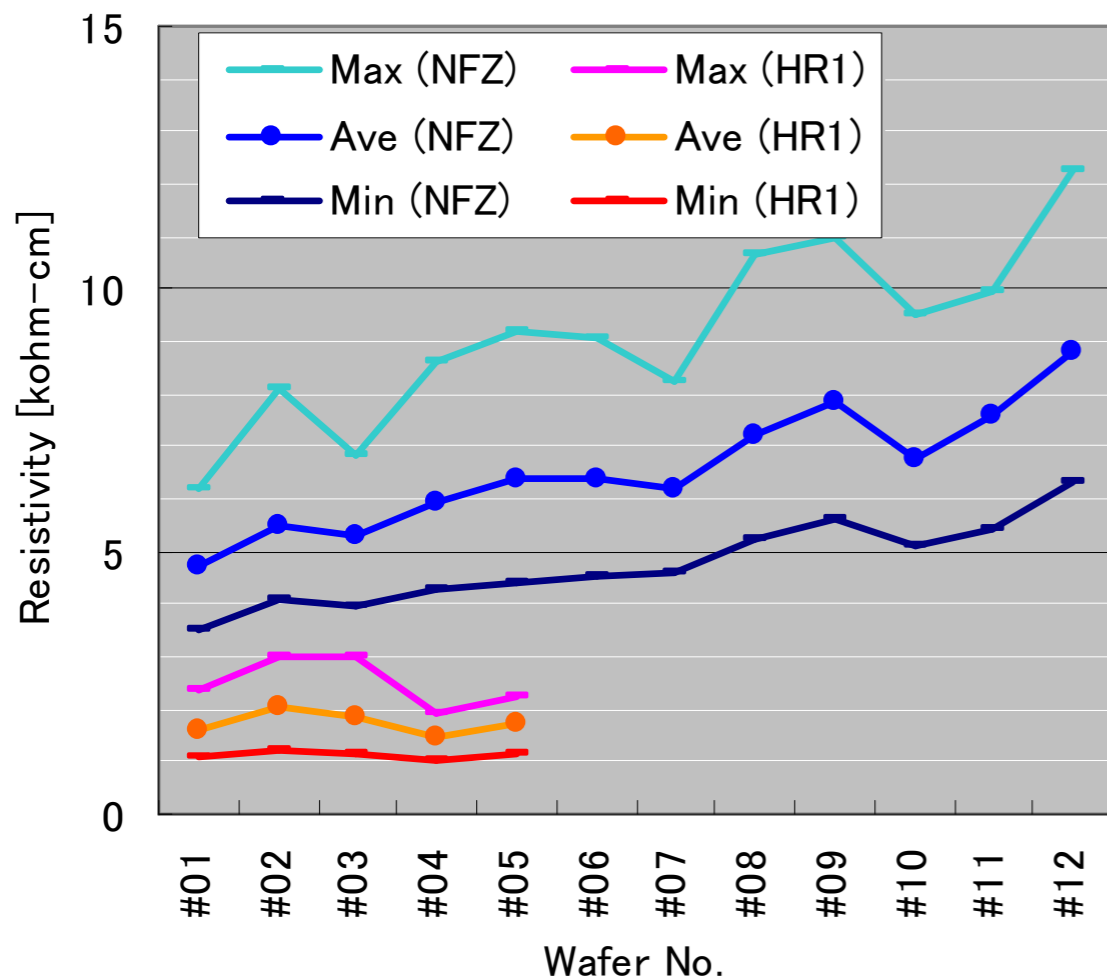
- 500μm @ VBB=200V
→ ρ=4kΩcm < average (7kΩcm)
- ρ is different from position to position on a wafer.
- Check which wafer used in this device.

b) MX1542-002JA (N型FZ)

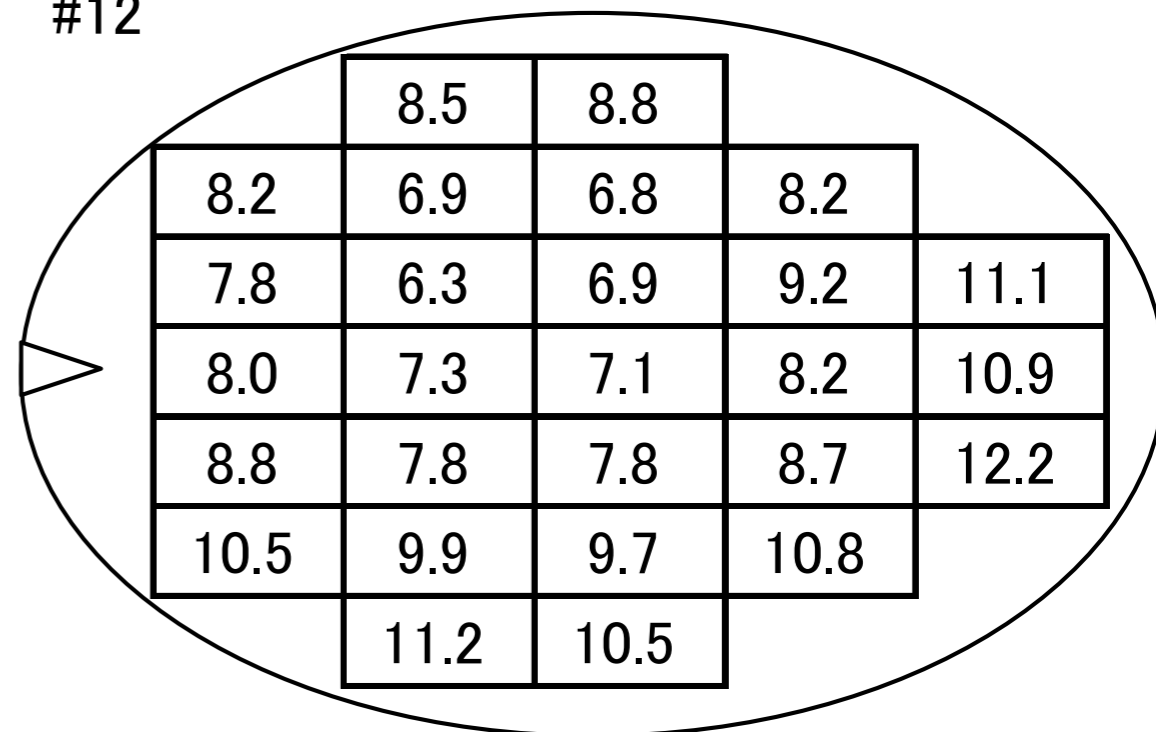
#01



b) 比抵抗のウェハバラツキ



#12



XRPIX I/Ib-FZ(2010/12)-FI (7kΩcm) : Dark (Leak) Current

- XRPIX I-FZ(2010)

- Wafer Thickness 260μm

Consists of two components.

(1) Depend on T and V_{BB}.
generation in depletion layer.

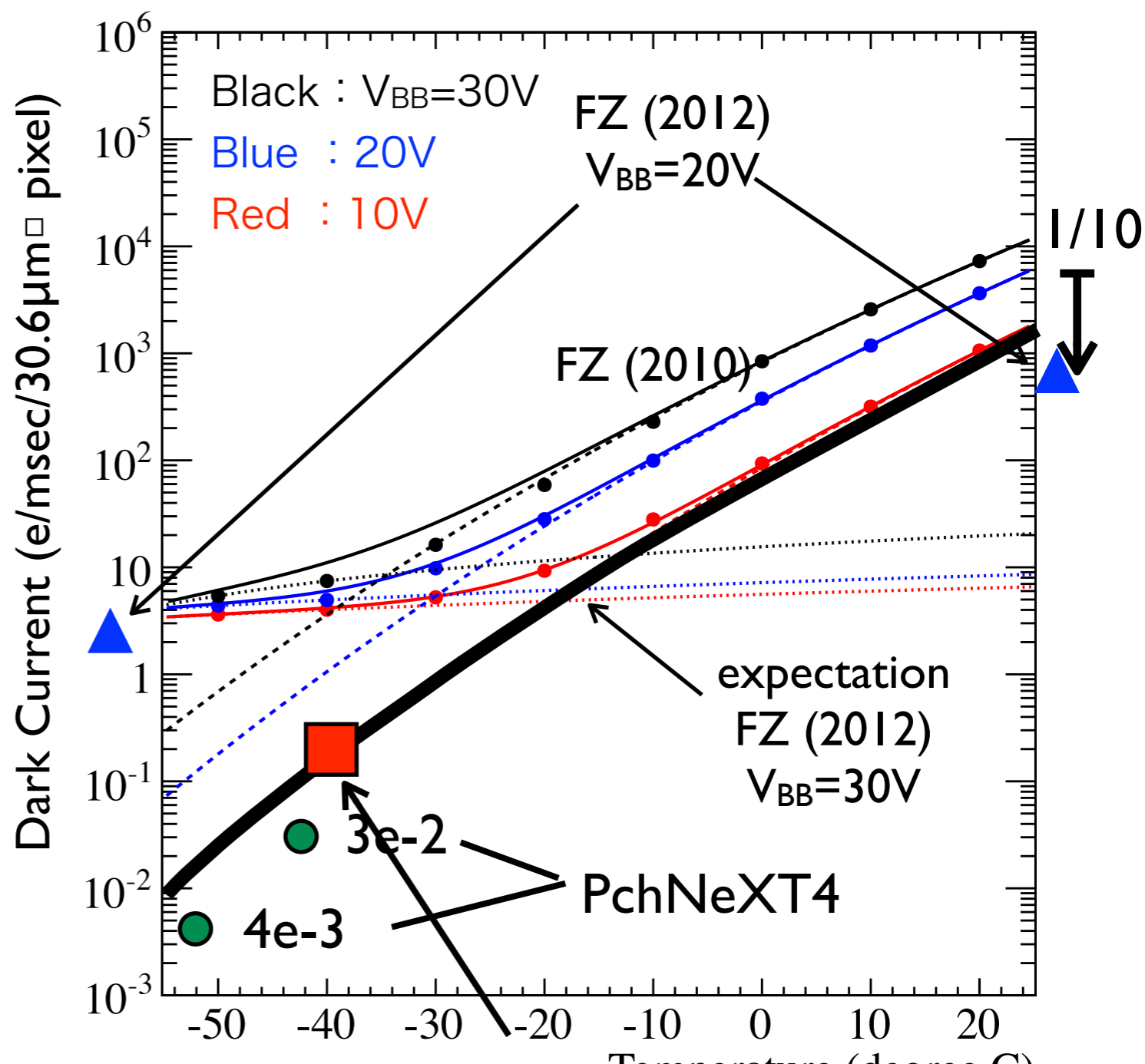
(2) Almost Constant.

$10\text{e/msec} = 1.6\text{fA}$

⇒ Next Slide

- XRPIX Ib-FZ(2012)

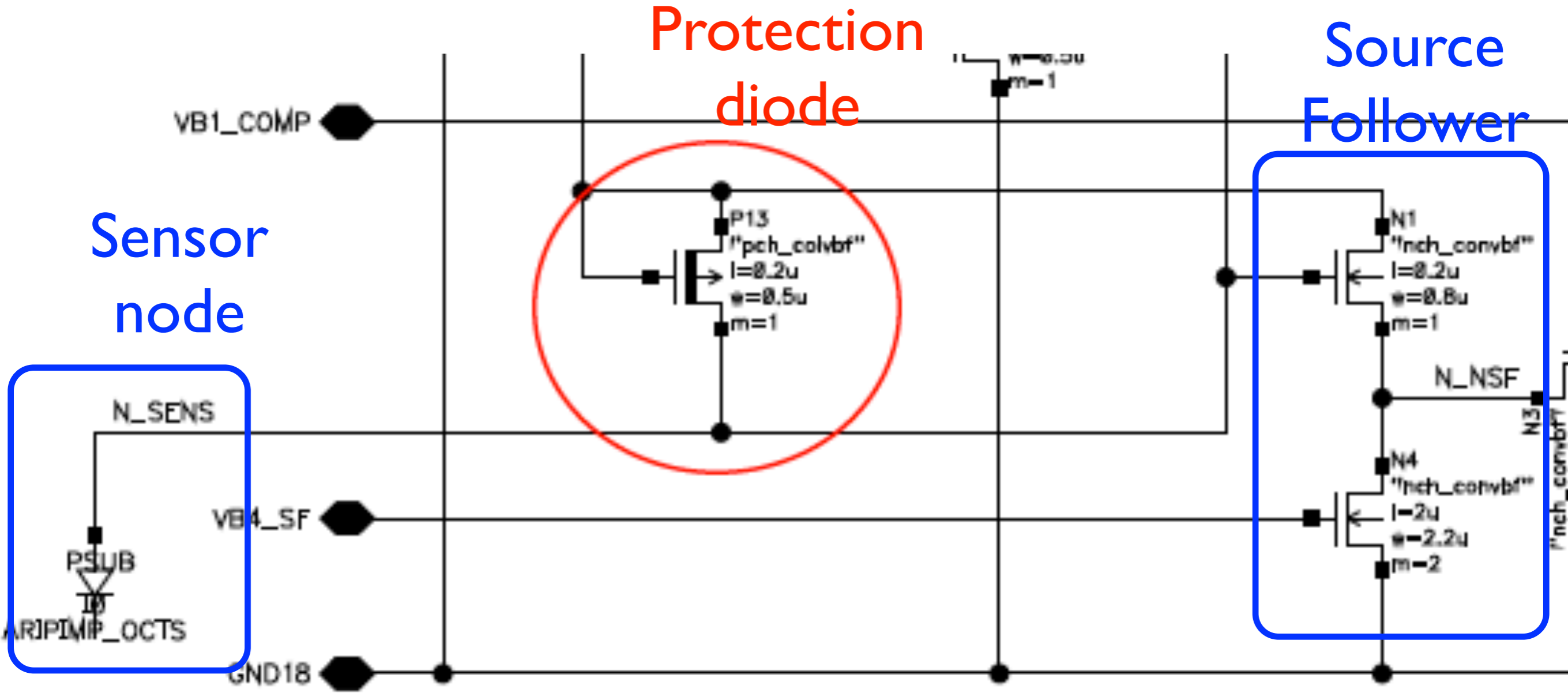
- Dark is 1/10 of FZ(2010)
(at the same V_{BB})



Eliminating the constant component
 ⇒ reach the target specification.

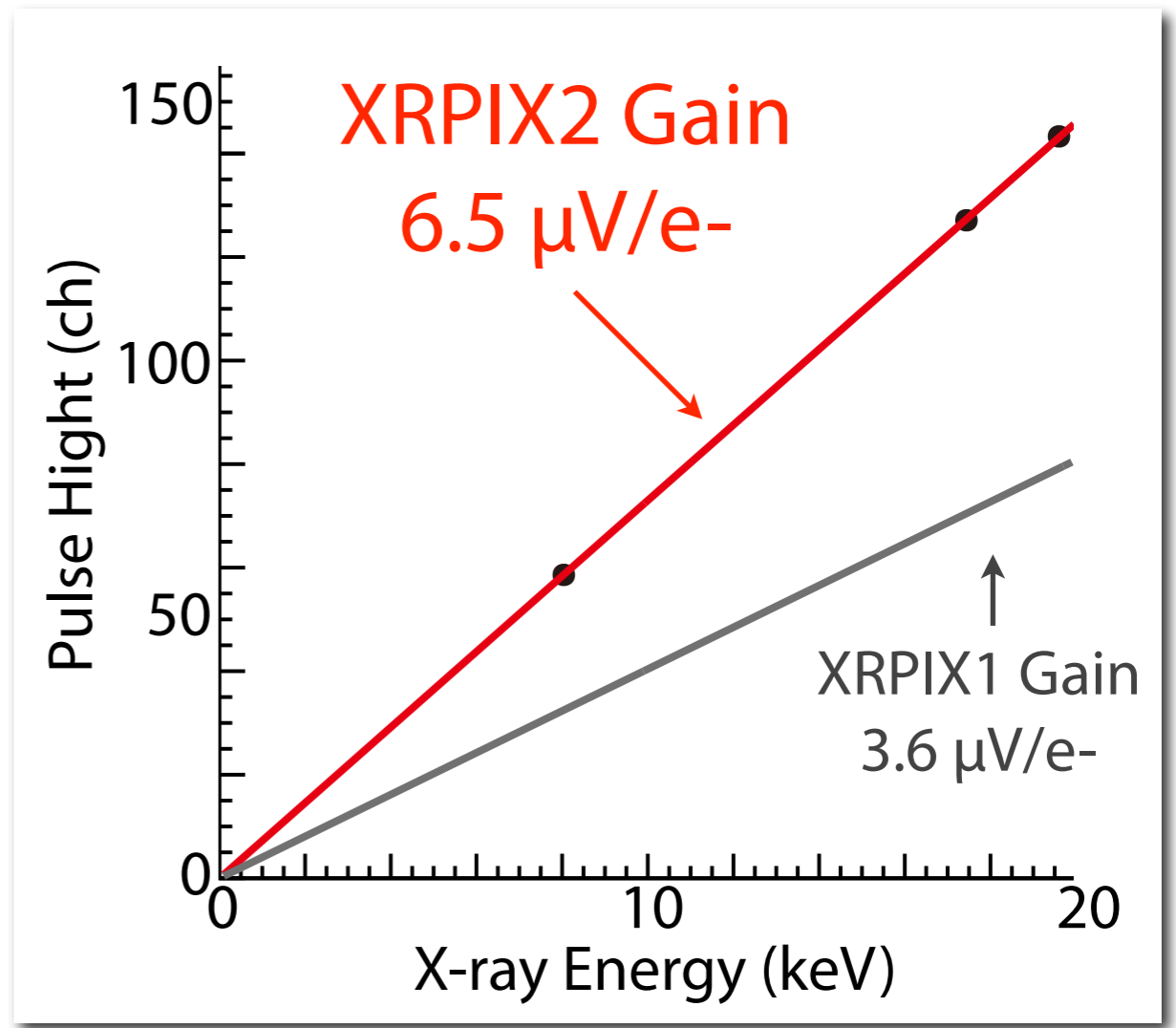
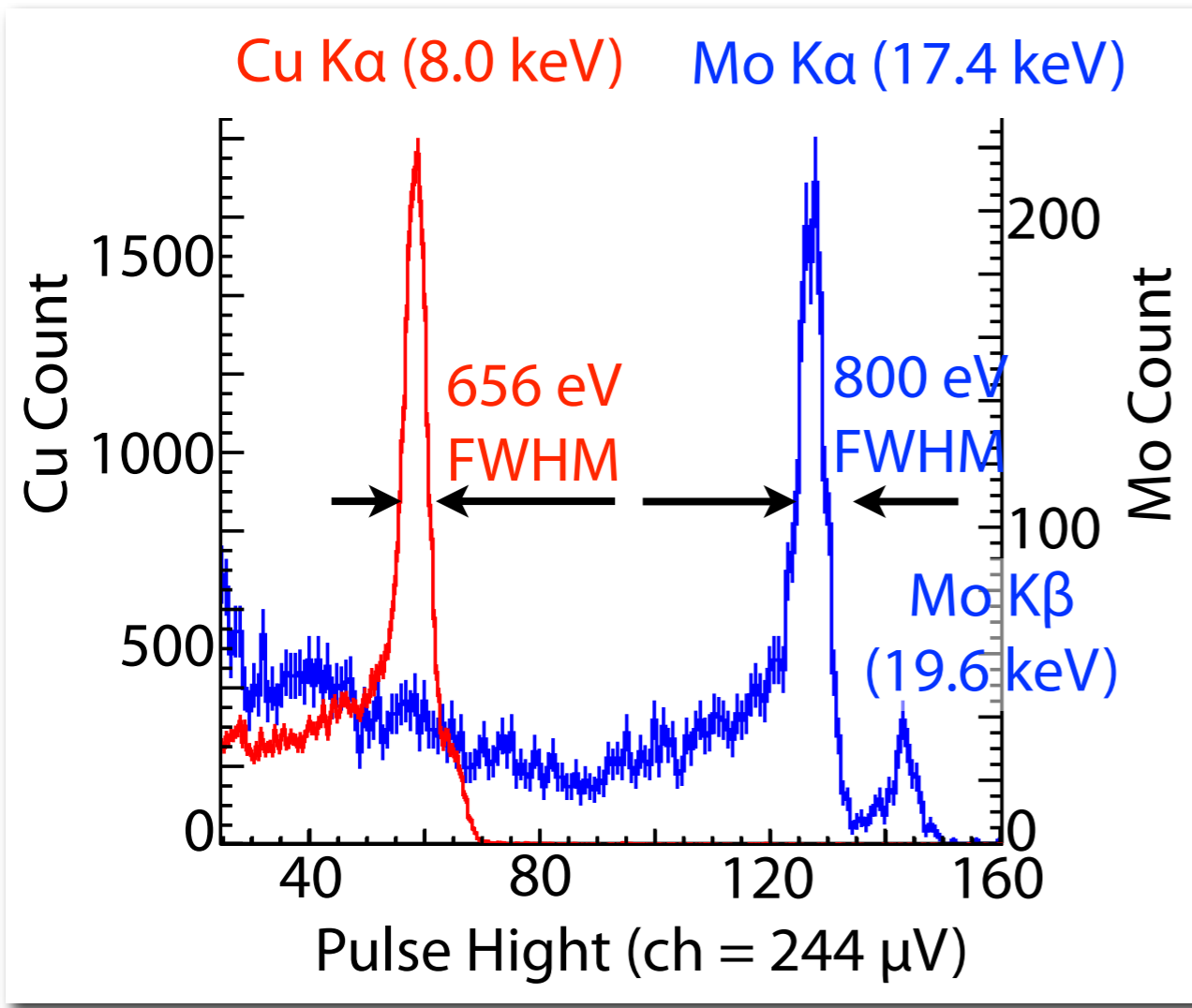
Target Spec. at -40C (depletion 250μm)
 = 0.1 e/1msec/30.6μm² = 2pA/cm²

Leak Current from Protection Diode (Arai-sensei)



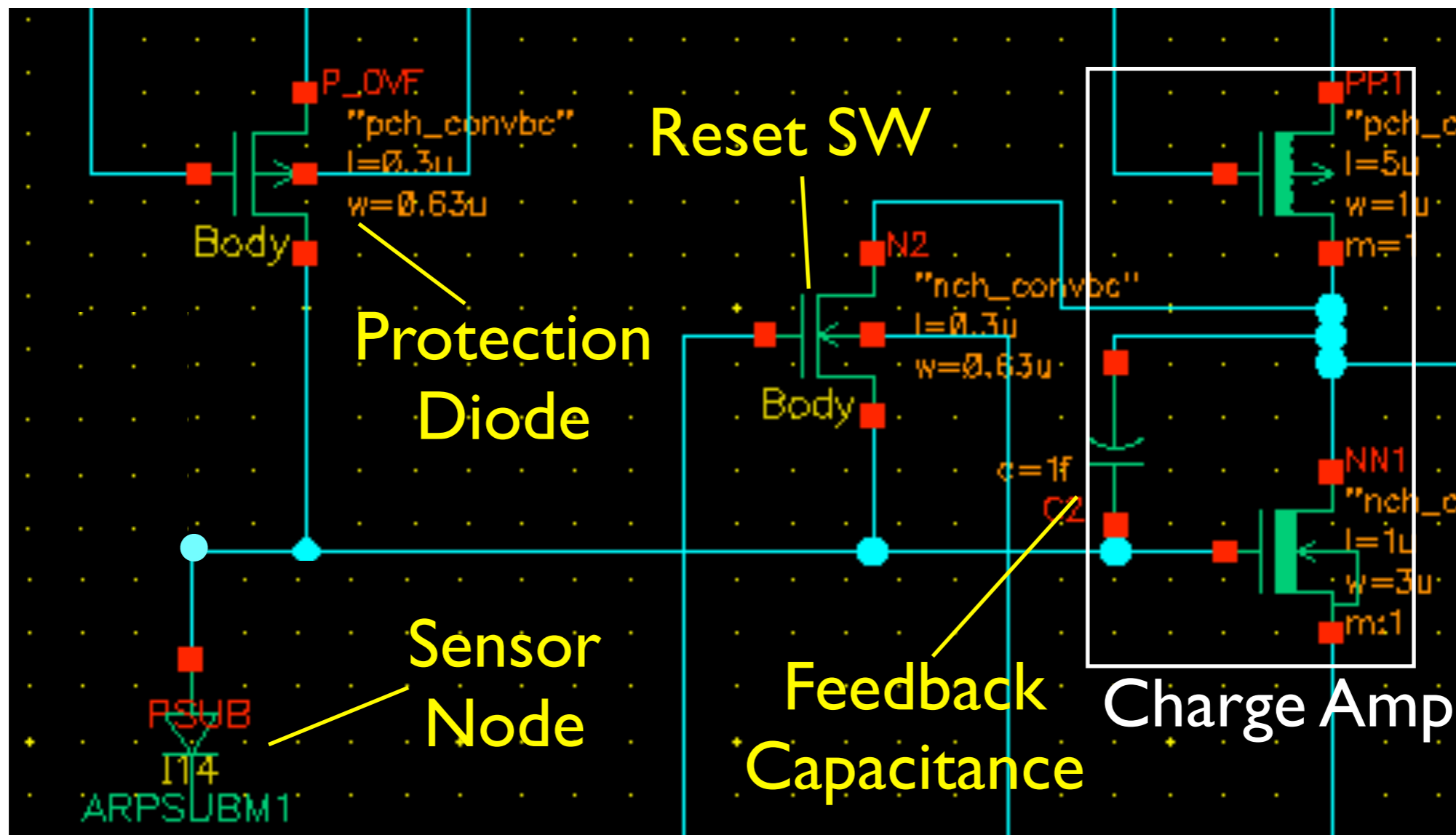
- Simulation shows leak current from PMOS used as a protection diode at the sensor node is $2\text{fA} = 12.5\text{e}/\text{msec}$.
- Possibly explains the constant component.
- Gate length of the PMOS = $0.2\mu\text{m} \rightarrow 1\mu\text{m}$.
 \Rightarrow Reduce leak current $2\text{fA} \rightarrow 0.02\text{fA}$.

XRPIX2-CZ-FI (Small Pixel) : Spectrum



	Observed	Readout Noise	Fano Noise	Pixel-Pixel Gain Dispersion 1%	Sum
Cu K α	656 eV	548 eV (FWHM) 64 e-(rms)	139 eV	255 eV	620 eV
Mo K α	800 eV		205 eV	553 eV	805 eV

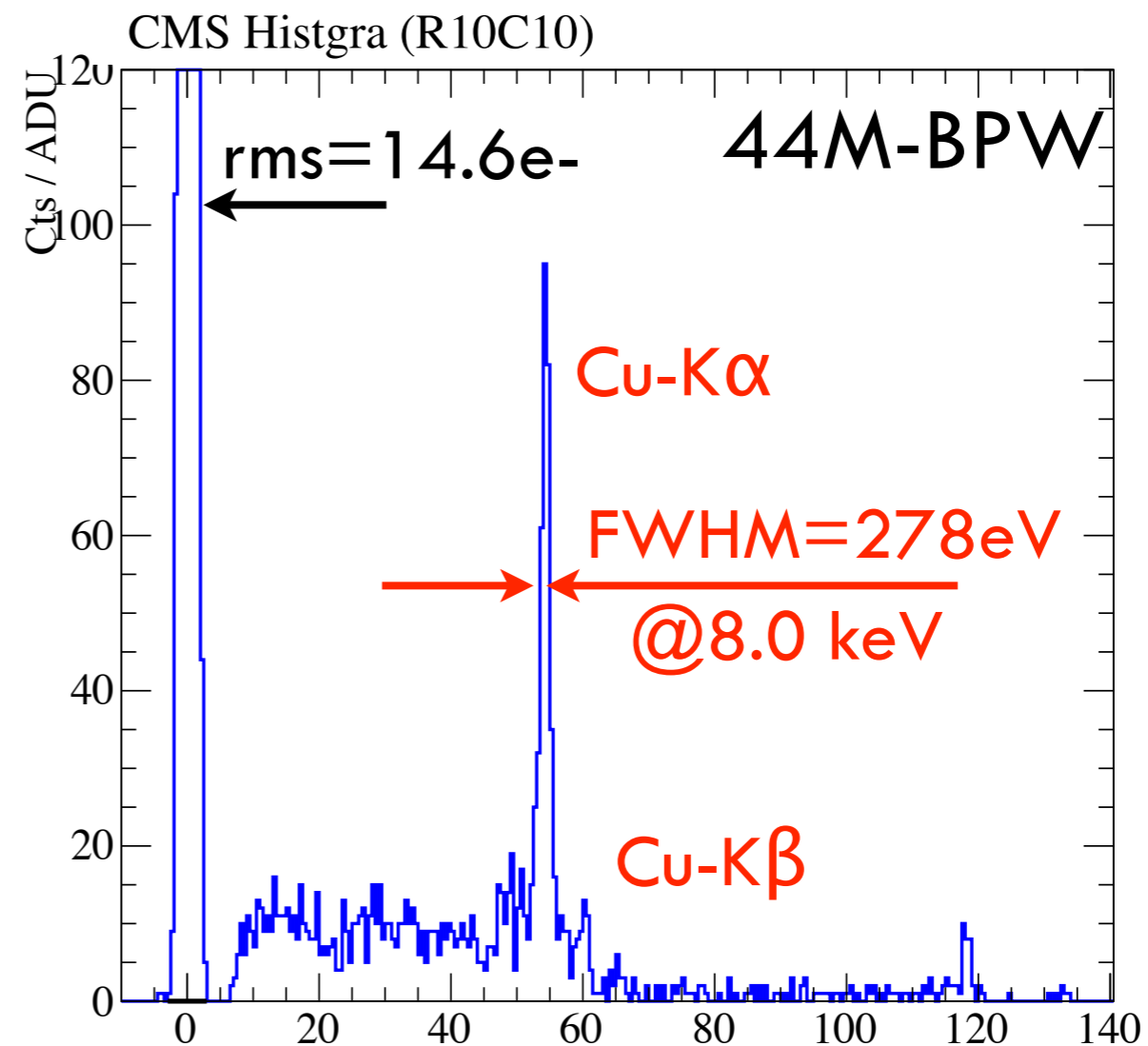
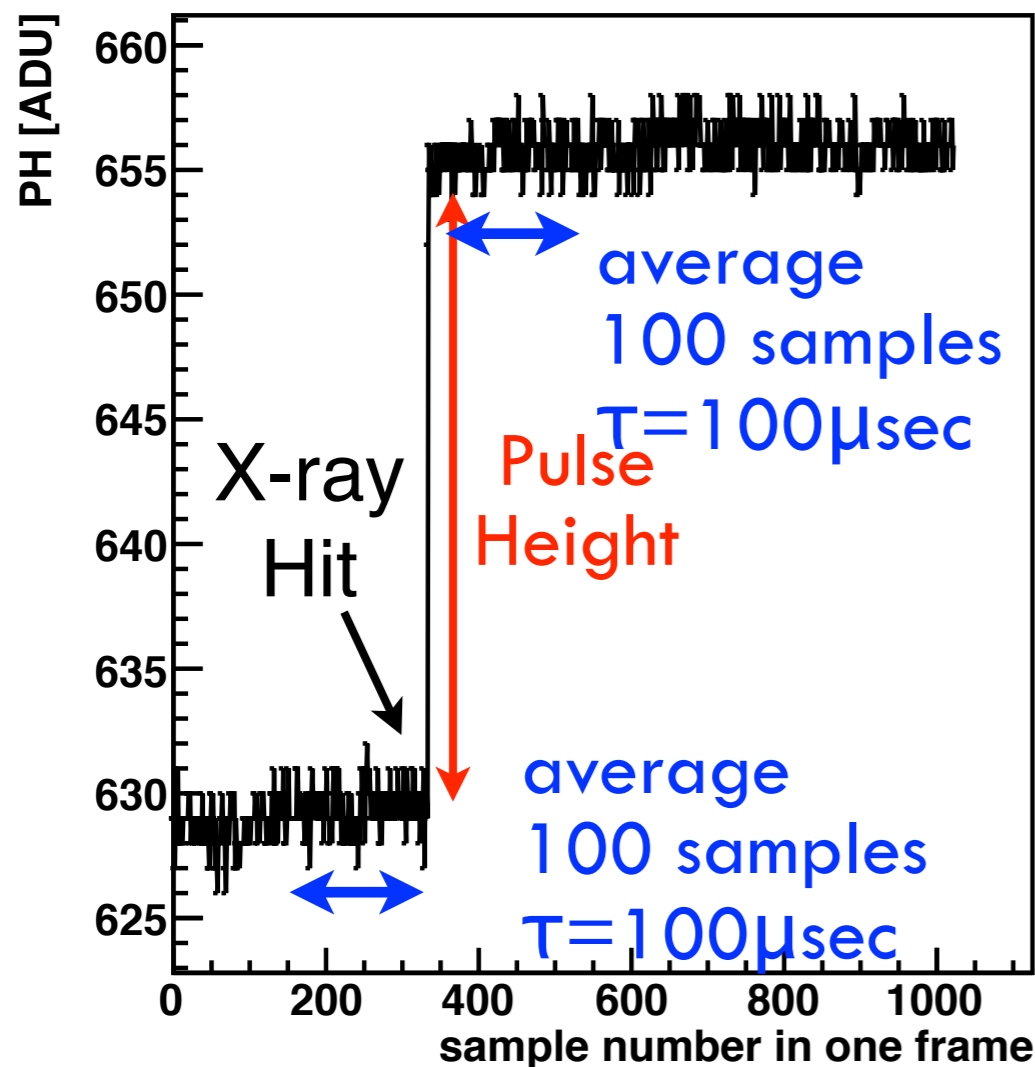
Coming Soon I / Pre Amp in Each Pixel



XRPIX3

- A charge sensitive amp in every pixel in order to increase the gain.
- This is basically the same amp used in PIXOR.
- Gain $\sim 100 \mu\text{V}/e$, higher by a factor of ~ 15 .
- Readout noise = $64e$ (rms) $\rightarrow \sim 4e$ (rms).

- In order to study the soft X-ray performance.
- Observe the waveform of analogue output from a single pixel by fixing the readout address without clocking (Single Pixel Readout like a SSD).
- Detect an X-ray as a “step” and measure the pulse height. → X-ray spectrum.
- No reset during the measurement → Free from the reset noise
- Reduce noises other than the reset noise by introducing LPF.
high_v(100 samples average) - low_v(100 samples average) → LPF with $\tau=100\mu\text{s}$

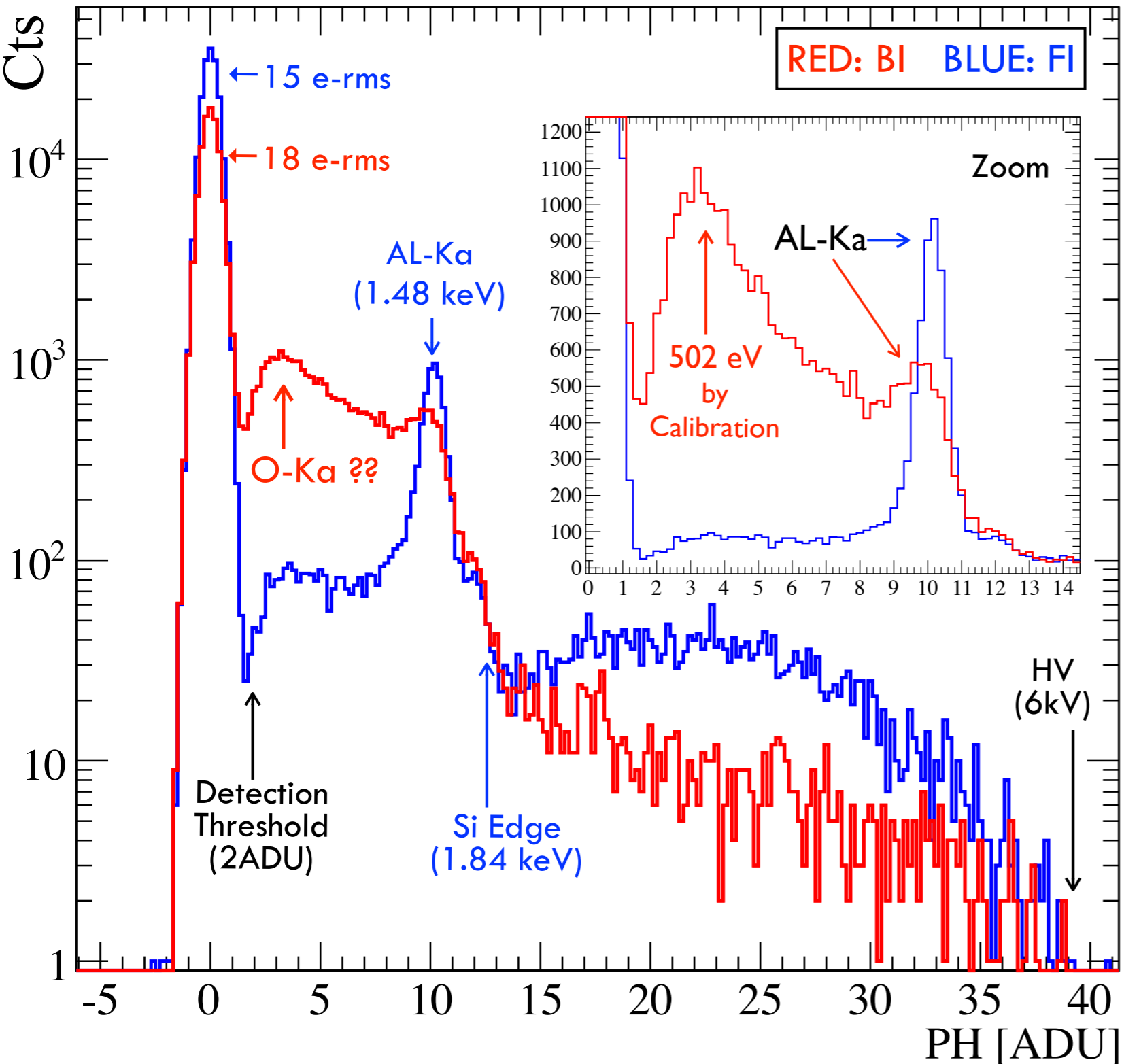


$\Delta E = 278\text{eV @ } 8.0\text{keV (FWHM), readout noise} = 14.6\text{e (rms)}$

XRPIX Ib-CZ-FI/BI (100 μ m): Spectra in Single Pixel Readout (2011.11.22)

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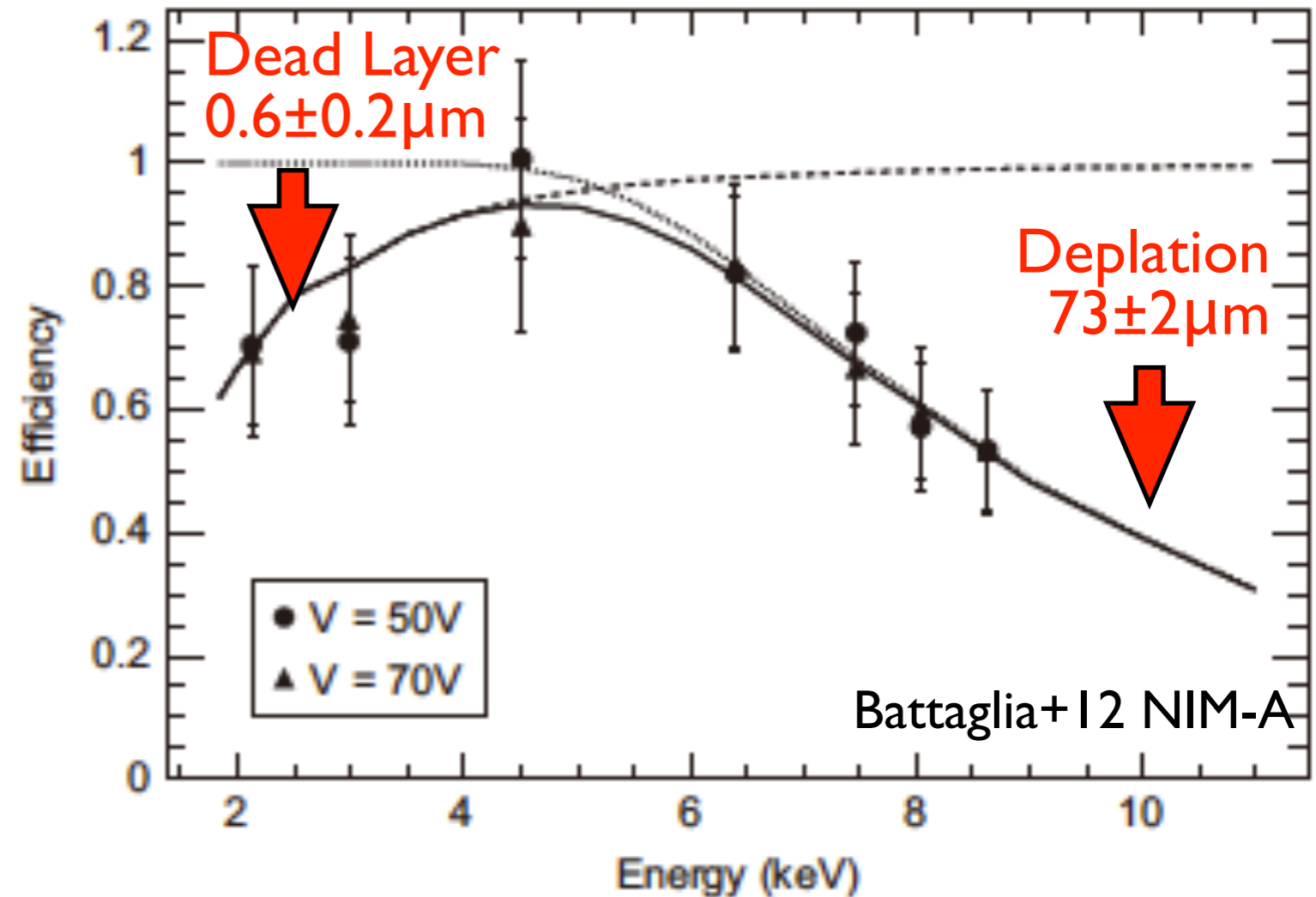
Target= Al₂O₃ , Front-I, Back-I, V_{tube}=6 kV,
 V_{bais} = 100V, Temp=-50°C, Hit Threshold= 2 ADU, Exposure=400 sec, PIX=R10C10, 2 μ s_{sample}, 300 μ s_{ave}



- Back illumination type.
- X-ray generator (target = Al, 6kV).
- Al-K + Bremss (+O-K from Al₂O₃?)
- ΔE (FI) = 188eV,
 ΔE (BI) = 351 eV (if line)
- Absolute and relative X-ray Fluxes are uncalibrated.
 → QE and dead layer thickness are unknown.

- Pizza Proc. is the back side process developed by LBNL.
- CZ-BI with Back-thinned to $70\mu\text{m}$.
- A thin phosphor layer is implanted.
- Dead Layer : $0.6\pm 0.2\mu\text{m}$

QE of LBNL's BI-SOIPIX / SOImager-2-CZ-BI



Pizza Process to FZ devices of XRPIX

- The Pizza proc. is now being made at LBNL.
- Evaluation of low energy X-ray spectral performance.

Summary

- We have been developing monolithic SOI sensor 'XRPIX' for future X-ray Astronomical Satellites.
- It contains the function of trigger signal output for the anti-coincidence, which realizes very low non-X-ray BGD.
- We successfully developed the test devices with the depletion thickness of $\sim 250\mu\text{m}$.
- Under going
 - Improvement of the readout noise.
 - Reduction of dark current.
 - Test with new back side process (Pizza Proc.).



A-R-Tec
Analog and RF Technologies